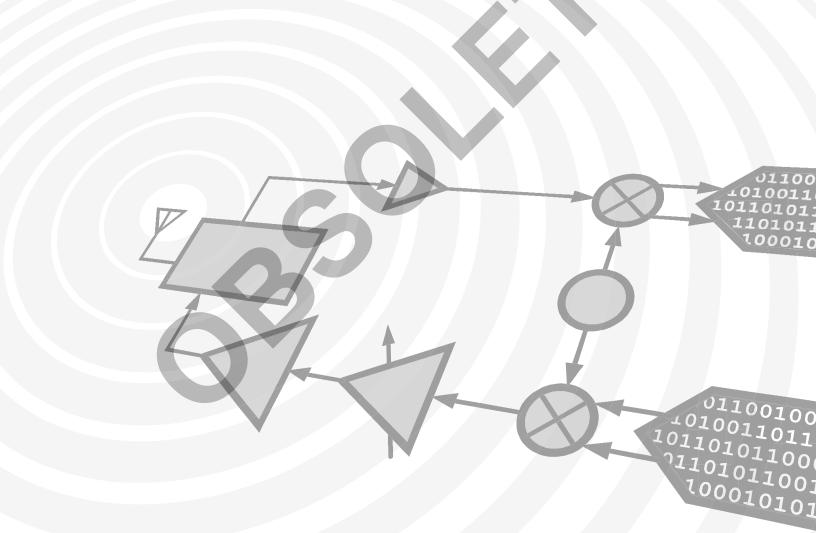




# Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED









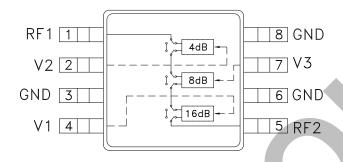


# Typical Applications

The HMC230MS8 / HMC230MS8E is ideal for:

- Cellular
- PCS, ISM, MMDS
- WLL Handset
- Base Station Infrastructure

# **Functional Diagram**



#### **Features**

4 dB LSB Steps to 28 dB Single Positive Control Per Bit ±0.5 dB Typical Bit Error Pin - For - Pin Replacement to AA100-59 Digital Attenuator

#### General Description

The HMC230MS8 & HMC230MS8E are broadband 3 - bit positive control GaAs IC digital attenuators in 8 lead MSOP surface mount plastic packages. Covering 0.75 to 2 GHz, the insertion loss is typically less than 2 dB. The attenuator bit values are 4 (LSB), 8, and 16 dB for a total attenuation of 28 dB. Accuracy is excellent at ±0.5 dB typical with an IIP3 of up to +48 dBm. Three bit control voltage inputs, toggled between 0 and +3 to +5 volts, are used to select each attenuation state at less than 50 uA each. A single Vdd bias of +3 to +5 volts applied through an external 5K Ohm resistor is required.

# Electrical Specifications,

 $T_A = +25^{\circ}$  C, Vdd = +3V to +5V & VctI = 0/Vdd (Unless Otherwise Stated)

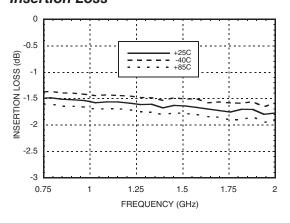
Parameter	Frequency	Min.	Typical	Max.	Units
Insertion Loss	0.75 - 1.7 GHz 1.7 - 2.0 GHz		1.6 1.8	1.8 2.1	dB dB
Attenuation Range	0.75 - 2.0 GHz		28		dB
Return Loss (RF1 & RF2, All Atten. States)	0.75 - 1.7 GHz 1.7 - 2.0 GHz	10 13	13 16		dB dB
Attenuation Accuracy: (Reference to Insertion Loss)					
4, 8, 12, 16, 20 dB States 24, 28 dB States All Attenuation States	0.75 - 1.4 GHz 0.75 - 1.4 GHz 1.40 - 2.0 GHz	$\pm$ 0.3 + 3% of Atten. Setting Max $\pm$ 0.4 + 6% of Atten. Setting Max $\pm$ 0.3 + 3% of Atten. Setting Max			dB dB dB
Input Power for 0.1 dB Compression 5V 3V	0.75 - 2.0 GHz		20 19		dBm dBm
Input Third Order Intercept 5V (Two-Tone Input Power = 0 dBm Each) 3V	0.75 - 2.0 GHz		46 45		dBm dBm
Switching Characteristics					
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)	0.75 - 2.0 GHz		560 600		ns ns



# 4 dB LSB GaAs IC 3-BIT DIGITAL ATTENUATOR, 0.75 - 2.0 GHz

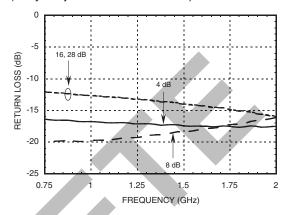


#### **Insertion Loss**



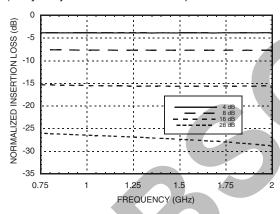
# Return Loss RF1, RF2

(Only Major States are Shown)

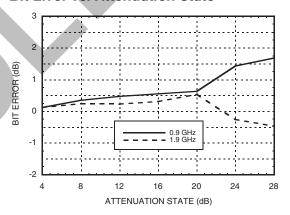


#### **Normalized Attenuation**

(Only Major States are Shown)

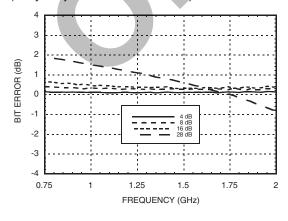


#### Bit Error vs. Attenuation State



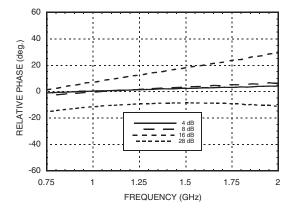
## Bit Error vs. Frequency

(Only Major States are Shown)



# Relative Phase vs. Frequency

(Only Major States are Shown)



Note: All Data Typical Over Voltage (+3V to +5V) & Temperature (-40 to +85 deg C).



# 4 dB LSB GaAs IC 3-BIT DIGITAL ATTENUATOR, 0.75 - 2.0 GHz



# **Control & Bias Voltages**

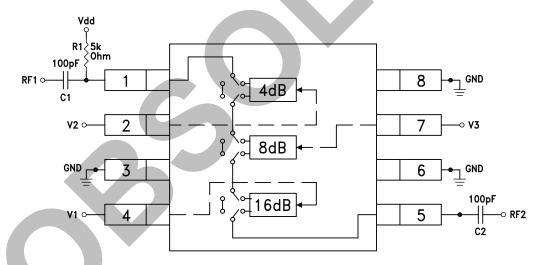
State	Bias Condition	
Low	0 to +0.2Vdc @ 20 uA Max	
High	Vdd ±0.2V @ 50 uA Typ	
Note: $Vdd = +3V \text{ to } +5V \pm 0.2V$		

#### **Truth Table**

Control Voltage Input		Input	Attonuation Catting	
V1 16 dB	V2 4 dB	V3 8 dB	Attenuation Setting RF1 - RF2	
High	High	High	Reference I.L.	
High	Low	High	4 dB	
High	High	Low	8 dB	
Low	High	High	16 dB	
Low	Low	Low	28 dB Max. Atten.	

Any combination of the above states will provide an attenuation approximately equal to the sum of the bits selected.

# **Application Circuit**



DC blocking capacitors C1 & C2 are required on RF1 & RF2. Choose  $C1 = C2 = 100 \sim 300 \text{ pF}$  to allow lowest customer specific frequency to pass with minimal loss. R1 = 5K Ohm is required to supply voltage to the circuit through either PIN 1 or PIN 5.





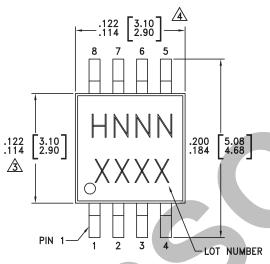
# 4 dB LSB GaAs IC 3-BIT DIGITAL ATTENUATOR, 0.75 - 2.0 GHz

# **Absolute Maximum Ratings**

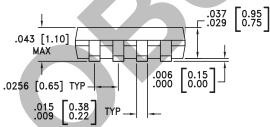
Control Voltage (V1, V2, V3)	Vdd to +0.5 Vdc
Bias Voltage (Vdd)	+8.0 Vdc
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
RF Input Power (0.75 - 2 GHz)	+26 dBm



# **Outline Drawing**







- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS].

.009 .003 0.22 0.08

- ⚠ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- M DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
  5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

## Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC230MS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H230 XXXX
HMC230MS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H230 XXXX

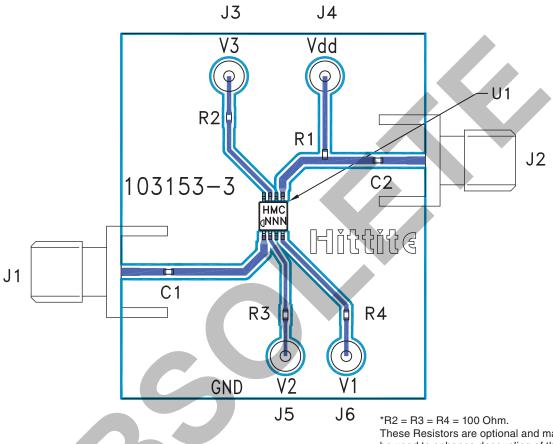
- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX





4 dB LSB GaAs IC 3-BIT DIGITAL ATTENUATOR, 0.75 - 2.0 GHz

## **Evaluation Circuit Board**



# These Resistors are optional and may be used to enhance decoupling of the RF path from the control inputs.

#### List of Materials for Evaluation PCB 103155 [1]

Item		Description	
J1 - J2		PCB Mount SMA Connector	
J3 - J6		DC Pin	
R1		5k Ohm Resistor, 0402 Chip	
R2, R3, R4	4	100 Ohm Resistor, 0402 Chip	
C1, C2		0402 Chip Capacitor, Select for Lowest Frequen of Operation	су
U1		HMC230MS8 / HMC230MS8E Digital Attenuator	
PCB [2]		103153 Evaluation PCB 1.25" x 1.5"	

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board as shown is available from Hittite Microwave Corporation upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350





4 dB LSB GaAs IC 3-BIT DIGITAL ATTENUATOR, 0.75 - 2.0 GHz

**Notes:** 

